EIAJ

日本電子機械工業会規格
Standard of Electronic Industries Association of Japan

EIAJ ED－7311-3A

集積回路パッケージ個別規格
（1.0mmピッチ T-BGA）
Standard of integrated circuits package
〔Tape Ball Grid Array1.0mm pitch(T-BGA)〕

１９９７年８月制定
１９９９年４月改正

作　成
半導体パッケージ標準化委員会
Technical Standardization Committee on Semiconductor Device Package

発　行
社団法人 日本電子機械工業会
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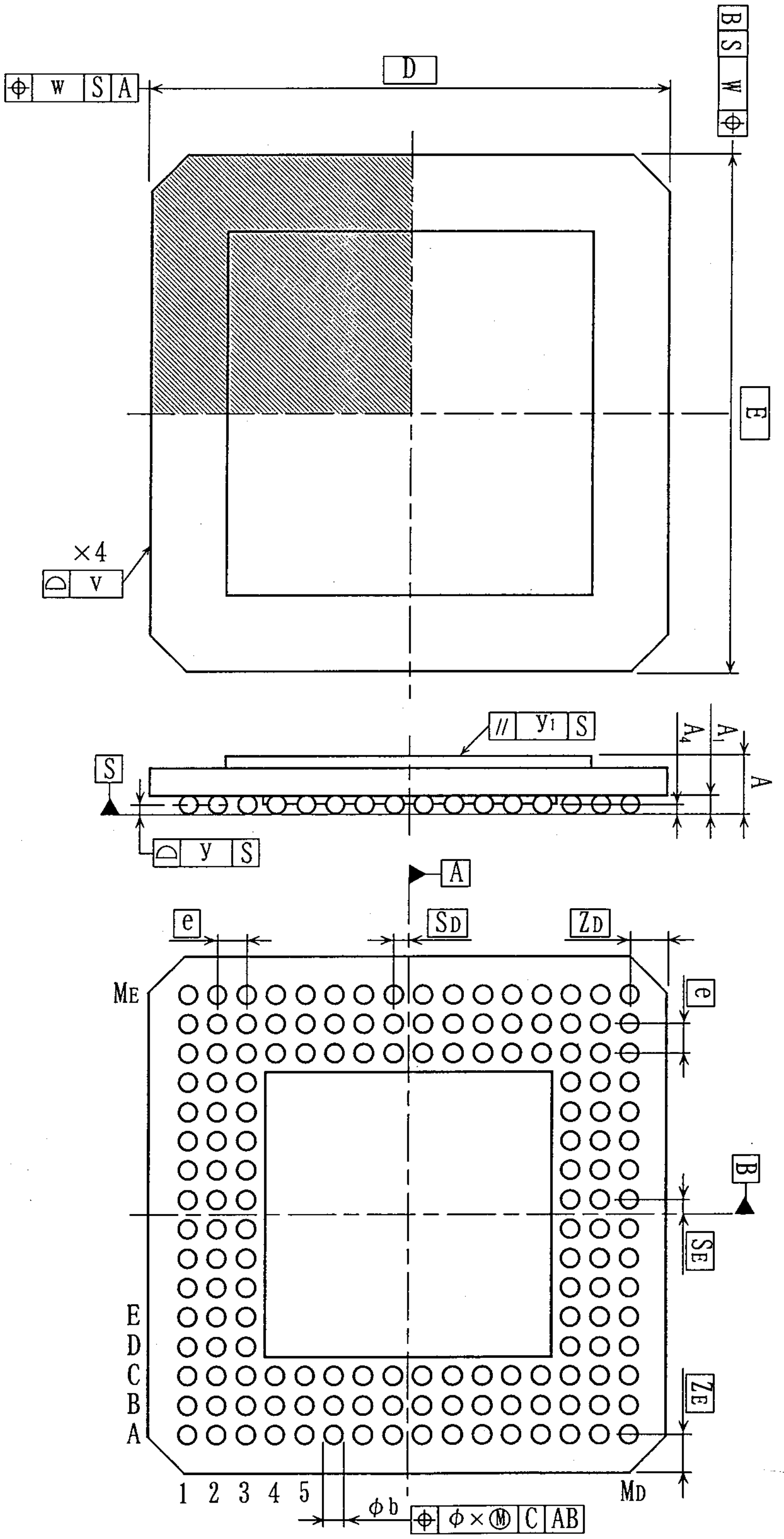

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PACKAGE NAME T−BGA(1. 0mm pitch)		EIAJ REGISTRATION NO. IC−7315−001	